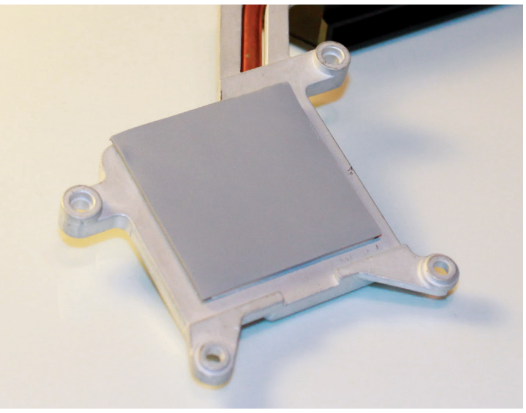
TG-X
Ultra Soft Thermal Conductive Pad



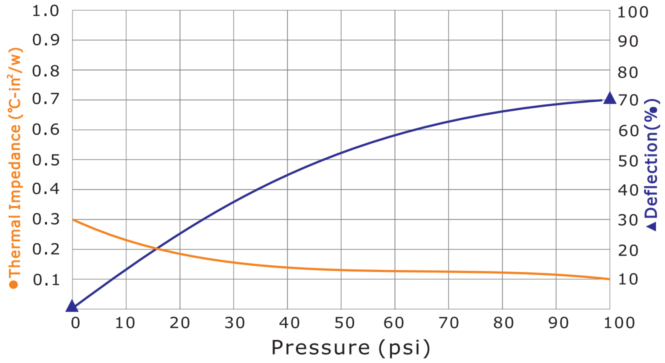
Features

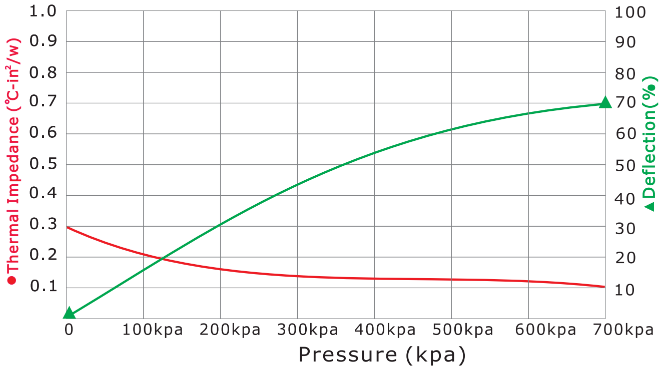
Superior thermal conductivity
Highly compressible
Naturally tacky
Low Shore 00 hardness
Low oil bleed
Electrically insulating

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection

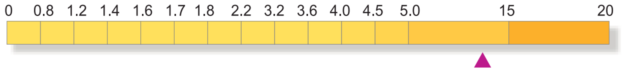




Properties

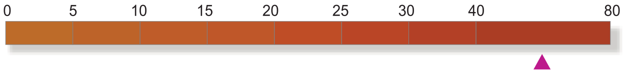
⬢ REACH Compliant
⬢ RoHS Compliant

Thermal Conductivity: 12 W/mK
(W/mK - Z Axis)



Testing sample thickness : 1.0 mm

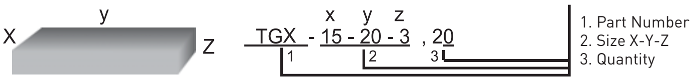
Hardness: 60 (Shore 00)
(Shore 00)



In the thermal resistance vs pressure vs deflection charts TG-X provides low thermal impedance.
As the pressure increases the thermal impedance decreases. TG-X provides good compliance and softness.

Property	TG-X	Unit	Tolerance	Test Method
Colour	Grey	-	-	Visual
Thickness (Available thickness range)	0.5 / 1.0	mm	-	ASTM D374
	0.0197 - 0.0394	inch	-	ASTM D374
Thermal Conductivity	12	W/mK	-	ASTM D5470
Flammability Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	12	kV/mm	-	ASTM D149
Weight Loss	‹1	%	-	ASTM E595
Specific Gravity	3.4	g/cm³	±0.2	ASTM D792
Working Temperature	-45 to 200	˚C	-	-
Volume Resistance	›10^{11}	Ohm-cm	-	ASTM D257
Standard Shape	-	Sheets 320-320mm	-	-
Hardness	60	Shore 00	±5	ASTM D2240

Available with an adhesive backing



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